

FIG. 1

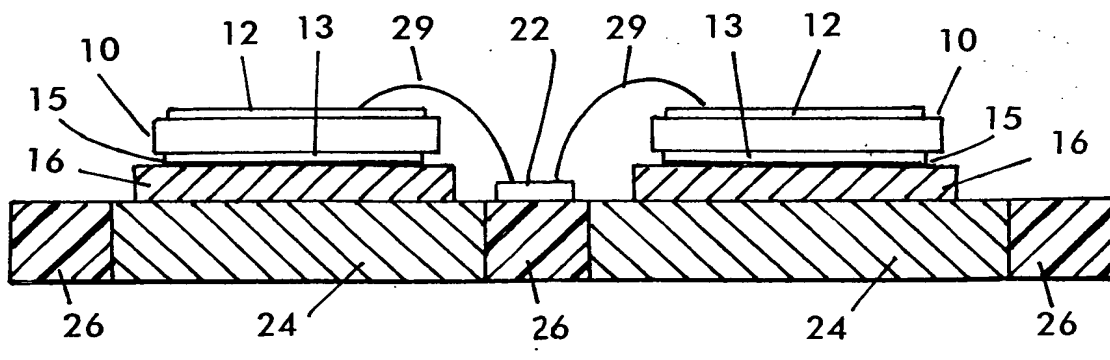


FIG. 2

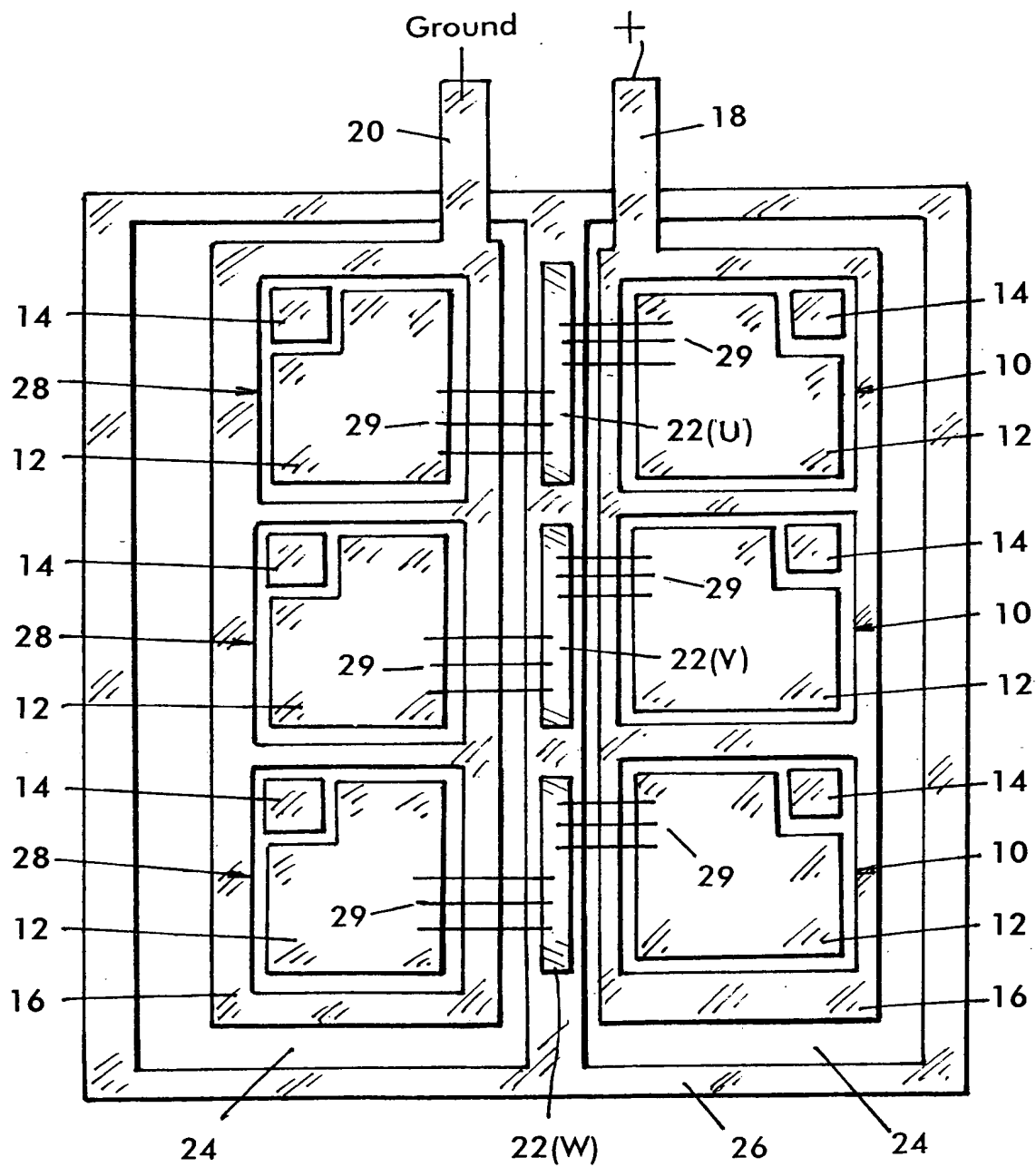


FIG. 3

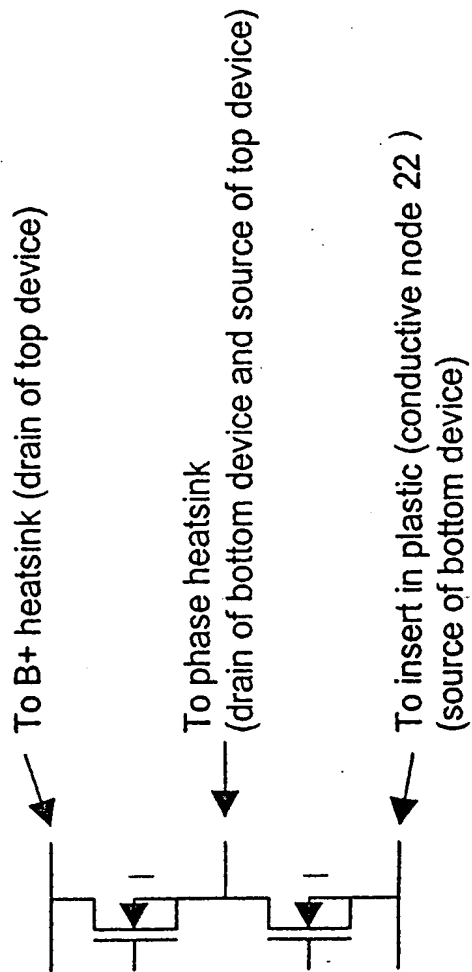


FIG. 4a

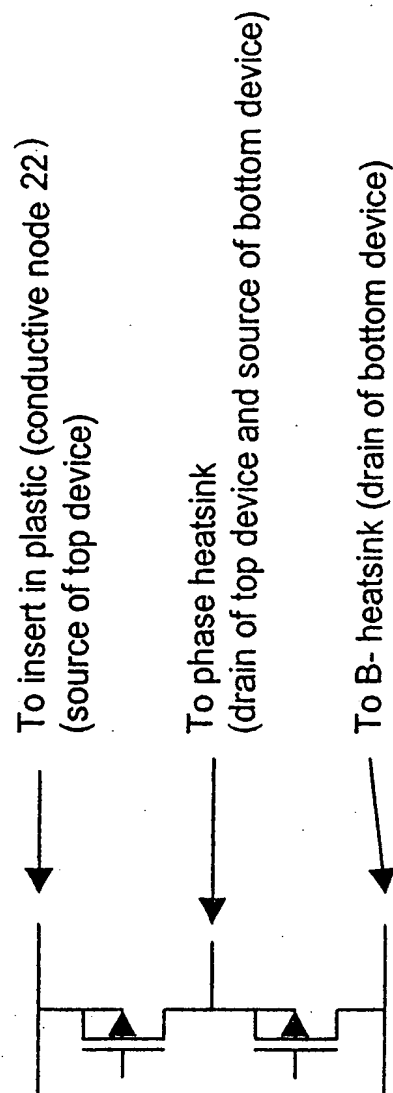
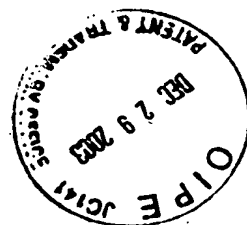


FIG. 4b

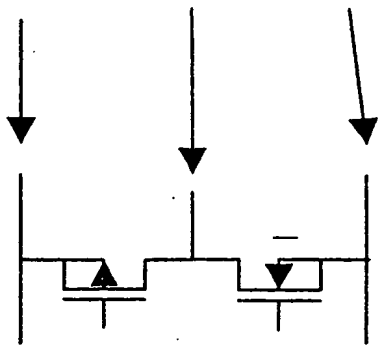


To insert in plastic (conductive node B+, similar to 22 of fig 3)
(source of top device)

To phase heatsink
(drain of top device and drain of bottom device)

To insert in plastic (conductive node 22, B-)
(source of bottom device)

FIG. 4c

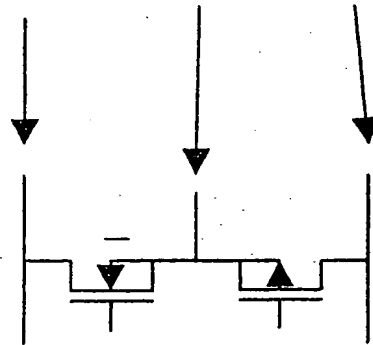


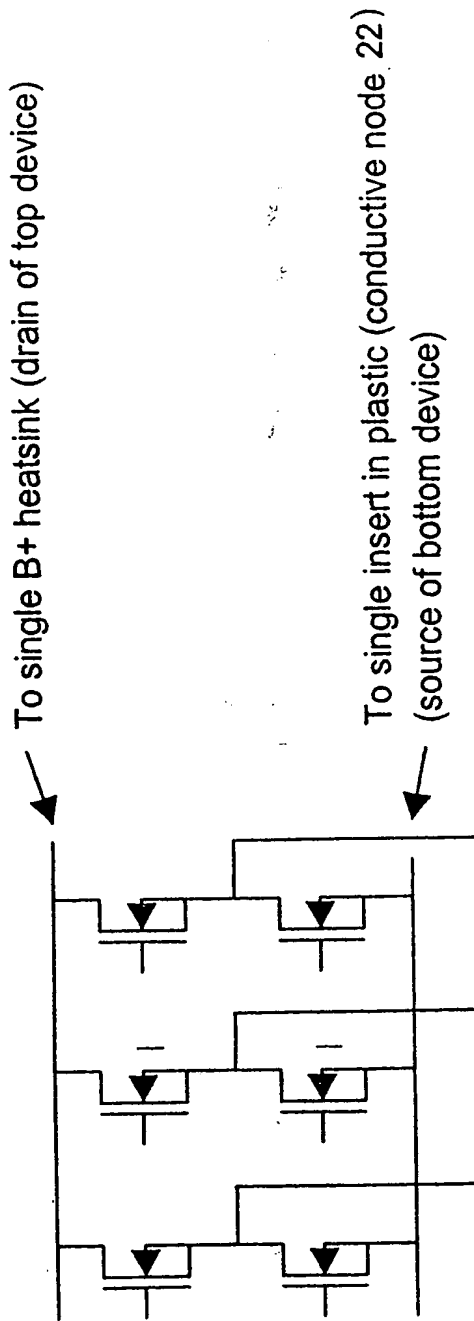
To B+ heatsink
(drain of top device)

To insert in plastic (conductive node 22)
(source of top device and source of bottom device)

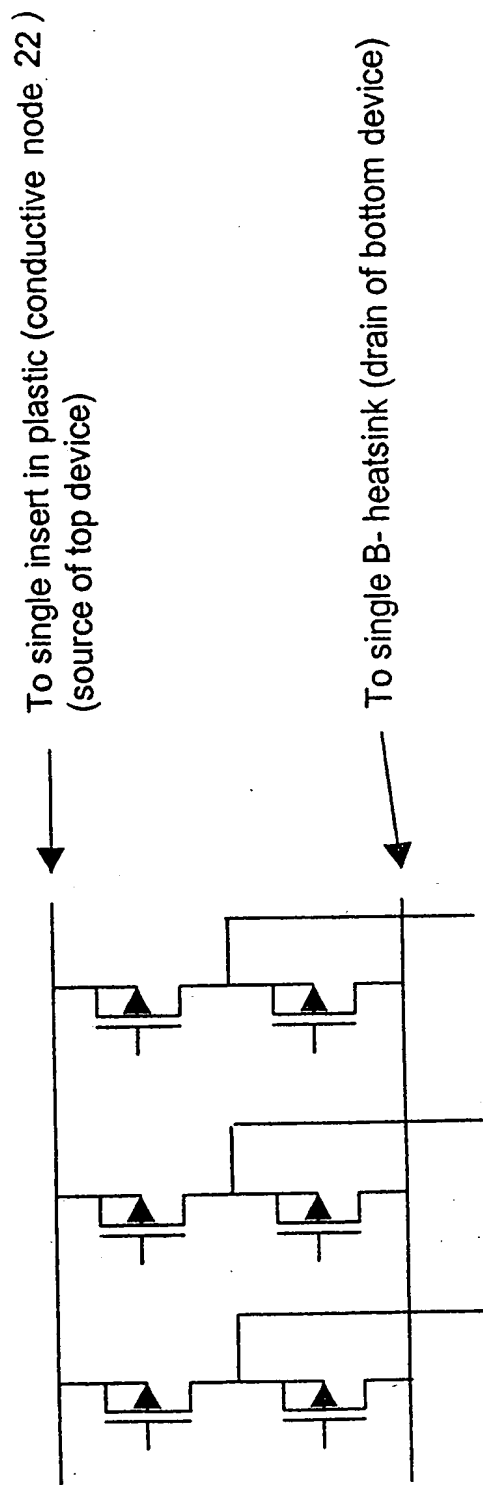
To B- heatsink
(drain of bottom device)

FIG. 4d





To phase heatsinks (3 heatsinks)
(drain of bottom device and source of top device,



To phase heatsinks (3 heatsinks)
(drain of top device and source of bottom device)

